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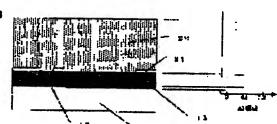
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54) NITRIDE SEMICONDUCTOR ELEMENT, METHOD FOR MANUFACTURING NITRIDE SEMICONDUCTOR CRYSTAL, AND NITRIDE SEMICONDUCTOR SUBSTRATE

57)Abstract:

'ROBLEM TO BE SOLVED: To form an AlGaN layer having uch a thickness that the layer can sufficiently function as a rystal growing base layer with a low defect density. OLUTION: A first AlGaN layer 13 is formed on a sapphire ubstrate 11 through a low-temperature buffer layer 12. Then second AlGaN layer 14 containing Al at a concentration wer than that of the first AlGaN layer 13 is formed on the yer 13. The layer 14 is grown while a facet structure is ormed from the opening of a mask 21. The thickness of the yer 14 is adjusted to ≥5 μm.



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